

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1 – 53 (Cancelled)

54. (currently amended) An acoustic transducer, comprising:

a substrate;

a micromachined ~~membrane~~ mesh fabricated on said substrate;

a layer of material sealing said ~~membrane~~ mesh to form a flexible diaphragm; and  
electronics connected to said diaphragm.

55. (currently amended) The transducer of claim 54 wherein said micromachined ~~membrane~~ mesh includes a serpentine shaped spring.

56. (previously presented) The transducer of claim 55 wherein said serpentine shaped spring is comprised of a plurality of alternately positioned long and short arms.

57. (previously presented) The transducer of claim 56 wherein a longest side of each of said long arms is less than approximately 50 microns in length.

58. (previously presented) The transducer of claim 56 wherein a maximum spacing between adjacent arms is approximately 3 microns.

59. (previously presented) The transducer of claim 54 wherein said micromachined member includes a plurality of cells, each cell comprised of a plurality of serpentine shaped springs.

60. (previously presented) The transducer of claim 54 wherein the substrate is selected from a group consisting of ceramic, glass, silicon, printed circuit board, and silicon-on-insulator semiconductor devices.

61. (previously presented) The transducer of claim 54 wherein said layer of material is selected from a group consisting of polymer sealants.

62. (previously presented) The transducer of claim 54 wherein the diaphragm is supported by the substrate such that changes in air pressure result in movement of the diaphragm, and wherein said electronics senses the movement of said diaphragm and converts said movement into electrical signals.

63. (previously presented) The transducer of claim 54 wherein the diaphragm is supported by the substrate such that said electronics applies an electrical signal to said diaphragm, and wherein said diaphragm converts said electrical signal into an acoustic wave.

64. (previously presented) The transducer of claim 54 wherein said electronics comprises an input circuit coupled to said diaphragm for actuating said diaphragm with an electrical input.

65. (previously presented) The transducer of claim 64 wherein said input circuit comprises:  
a digital signal processor (DSP) having a first input terminal for receiving input digital audio signals, a second input terminal for receiving a digital feedback signal indicative of displacement of said diaphragm, and a first output terminal, and wherein said DSP provides at said first output terminal a digital difference signal from said input digital audio signals and said digital feedback signal; and  
a pulse width modulator having an input terminal coupled to said first output terminal for receiving said difference signal, and an output terminal coupled to said diaphragm.

66. (previously presented) The transducer of claim 65 wherein said pulse width modulator converts the digital difference signal into a 1-bit pulse width modulated (PWM) signal, and wherein said pulse width modulator applies via its output terminal the 1-bit PWM signal to said diaphragm as an electrical input.

67. (previously presented) The transducer of claim 65 wherein said electronics further comprises a feedback circuit coupled to said DSP and said diaphragm, and wherein said feedback circuit generates said digital feedback signal.

68. (previously presented) The transducer of claim 67 wherein said input digital audio signals, said digital feedback signal, and said digital difference signal are pulse code modulated (PCM) signals.

69. (previously presented) The transducer of claim 67 wherein said feedback circuit includes a sense amplifier coupled to said diaphragm and an analog to digital converter coupled between said sense amplifier and said DSP.

70. (previously presented) The transducer of claim 69 wherein said sense amplifier includes a pressure sensor.

71. (previously presented) The transducer of claim 70 wherein said pressure sensor includes a CMOS MEMS microphone.

72. (previously presented) The transducer of claim 70 wherein said sense amplifier includes a position sensor.

73. (previously presented) The transducer of claim 69 further comprising a housing carrying the substrate and at least one of said DSP, said pulse width modulator, said sense amplifier and said analog to digital converter.

74. (previously presented) The transducer of claim 69 wherein at least one of said DSP, said pulse width modulator, said sense amplifier and said analog to digital converter is fabricated onto said substrate.

75. (previously presented) An acoustic transducer, comprising:

a substrate;

a micromachined membrane fabricated on said substrate;

a layer of material sealing said membrane to form a flexible diaphragm;

an input circuit for actuating said diaphragm; and

a feedback circuit coupled between said diaphragm and said input circuit.

76. (previously presented) The transducer of claim 75 wherein said substrate includes a backhole extending through said substrate and positioned under said flexible diaphragm.

77. (previously presented) The transducer of claim 75 wherein said input circuit includes a digital signal processor (DSP) and a circuit for applying an output of said DSP to said diaphragm.

78. (previously presented) The transducer of claim 77 wherein said DSP periodically outputs a test frequency to measure acoustic impedance, and wherein said DSP uses said measured acoustic impedance in the production of its output signal.

79. (previously presented) The transducer of claim 75 wherein said feedback circuit includes a sense amplifier coupled to said diaphragm and an analog to digital converter coupled between said sense amplifier and said input circuit.

80. (previously presented) The transducer of claim 79 wherein said sense amplifier includes a pressure sensor.

81. (previously presented) The transducer of claim 80 wherein said pressure sensor includes a CMOS MEMS microphone.

82. (previously presented) The transducer of claim 79 wherein said sense amplifier includes a position sensor.

83. (previously presented) The transducer of claim 75 further comprising a housing carrying the substrate and at least one of said input and said feedback circuits.

84. (previously presented) The transducer of claim 75 wherein at least one of said input circuit and said feedback circuit is fabricated on said substrate.

85. (previously presented) A method of audio reproduction, comprising:

electrostatically biasing a MEMS diaphragm, said diaphragm fabricated on a supporting substrate in a first plane; and

providing an electrical audio input signal to said diaphragm to cause said diaphragm to move in a direction perpendicular to said first plane.

86. (previously presented) The method of claim 85 additionally comprising:  
measuring the displacement of the diaphragm to produce a feedback signal;  
modifying the electrical audio input signal with said feedback signal.

87. (previously presented) The method claim 85 additionally comprising:  
periodically measuring an acoustic impedance; and  
modifying the electrical audio input signal in response to said measured acoustic impedance.